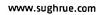
F 202.293.7860





Alan J. Kasper T 202-663-7903 akasper@sughrue.com

November 26, 2003



## MAIL STOP PATENT APPLICATION

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Re:

Application of Hien Boon TAN and Anthony Yi Sheng SUN

HIGH DENSITY CHIP SCALE LEADFRAME PACKAGE AND METHOD OF

MANUFACTURING THE PACKAGE

Assignee: UNITED TEST AND ASSEMBLY TEST CENTER LTD.

Our Ref. Q78432

Dear Sir:

Attached hereto is the application identified above comprising thirty five (35) sheets of the specification, including the claims and abstract, ten (10) sheets of drawings, a copy of an executed Assignment and PTO 1595 form, and a copy of an executed Declaration and Power of Attorney.

The Government filing fee is calculated as follows:

Total claims Independent claims Base Fee	<u>26</u> - 20 <u>7</u> - 3	=	6 x 4 x	\$18.00 = \$86.00 =	\$108.00 \$344.00 \$770.00
TOTAL FILING FEE Recordation of Assignment TOTAL FEE		·	·		\$1222.00 \$40.00 \$1262.00

Checks for the statutory filing fee of \$1222.00 and Assignment recordation fee of \$40.00 are attached. The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account. A duplicate copy of this transmittal letter is attached.



MAIL STOP PATENT APPLICATION November 26, 2003 Page 2

Benefit is claimed from:

Country

**Application No** 

Filing Date

U.S. Provisional

60/429,315

November 27, 2002

Respectfully submitted, SUGHRUE MION, PLLC

Attorneys for Applicant

By:

Alan J. Kasper

Registration No. 25,426

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WASHINGTON OFFICE 23373
CUSTOMER NUMBER

AJK/ars